Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	("20040188847").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/16 19:16
S2	1134	(257/762).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/11 12:28
S3	134	diode and dumet and (glass with seal$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 09:52
S4	11	dumet with ratio	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/11 15:31
S5	2	("6112386").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/11 15:33
S6	0	("jp6112386").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/11 15:34
S7	0	("jp306112386").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/07/11 15:34
S8	4	(diode with schottky) and dumet and (glass with seal$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 10:04

S9	134	diode and dumet and (glass with seal$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 09:54
S10	5	S9 and schottky	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 10:01
S11	204	("schottky barrier" with diode) and epitaxial and tungsten and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 10:50
S12	4	(diode with schottky) and dumet and (glass)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 10:05
S13	5	(diode and schottky) and dumet and (glass)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 10:07
S14	5	(diode and schottky) and dumet	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 10:07
S15	18685	(diode and schottky)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 10:07
S16	5	diode and schottky and dumet	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 10:09

S17	3	"glass-sealed" and schottky	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 10:09
S18	1594045	dumet and copper oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 10:50
S19	29	dumet and "copper oxide"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 11:17
S20	221	dumet and thick$4 and (copper or cuprous)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 11:12
S21	35	dumet with thick$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 11:12
S22	26	dumet with (copper or cuprous) adj oxide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/12 11:17
S23	801	wire with "copper oxide"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/16 19:16
S24	43	wire with "copper oxide" with thick$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/16 19:16

S25	37	(US-20020066959-$ or US-20020075125-$ or US-20020096764-$ or US-20020195941-$ or US-20030057559-$ or US-20030189249-$ or US-20040113273-$ or US-20040188847-$ or US-20040262760-$).did. or (US-3945111-$ or US-3987217-$ or US-4042951-$ or US-4495558-$ or US-4957370-$ or US-5164813-$ or US-5372886-$ or US-5623167-$ or US-5629564-$ or US-5656858-$ or US-5745330-$ or US-5777388-$ or US-6133136-$ or US-6184563-$ or US-6337522-$ or US-6344790-$ or US-6424036-$ or US-6426556-$ or US-6452270-$ or US-6462426-$ or US-6476494-$ or US-6570251-$ or US-6774495-$ or US-6819002-$ or US-6891274-$ or US-6911678-$). did. or (JP-54139476-$ or JP-56126979-$).did.	US-PGPUB; USPAT; JPO	OR	ON	2006/01/29 19:34
S26	2	dumet same copper near ratio	US-PGPUB; USPAT; JPO	OR	ON	2006/01/29 19:34
S27	3	dumet same copper near ratio	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/29 19:39
S28	152	dumet and glass with seal$3 with (temperature)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/29 19:41
S29	26	dumet same ratio	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/29 19:42
S30	68	dumet and electrode with copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/29 19:44

S31	2100	copper with wire and copper with ratio	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/29 19:47
S32	177	copper with wire and copper with ratio with "20"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/29 19:49
S33	108	copper with wire and copper with ratio and glass with seal$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/29 19:51
S34	14	copper with wire and copper with ratio and thermistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/29 19:52
S35	101	copper with wire and copper with ratio and diode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/29 19:59
S36	71	dumet and thermistor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/29 20:01
S37	49	wire with "copper ratio"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/29 20:15
S38	1	glass with "sealing temperature" with k2o	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/29 20:16

| S39 | 242 | glass with "sealing temperature" and (k2o or pbo or sio2) with glass | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/01/29 20:16 |